

04-30-2001



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PATENT

Docket No.: NAUP0280USA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECORDING COVER SHEET

- 1. Assignor: Yi-Fan Chen , Chi-King Pu , Shou-Kong Fan
- 2. Assignee: UNITED MICROELECTRONICS CORP.
No.3, Li-Hsin Road 2,
Science-Based Industrial Park,
Hsin-Chu, Taiwan, R.O.C.
- 3. Nature of Conveyance: Assignment of patent *04/18/01*
- 4. Reference number: Application filed herewith.
- 5. Correspondence to: Winston Hsu *09/836258*
5F, No. 389, Fu-Ho Rd.,
234 YungHo City, Taipei Hsien,
Taiwan, R.O.C.
- 6. Number of applications affected by this recording: 1
Total fee: (1 x \$ 40) = \$ 40.00 Payment by check enclosed
Authorization is hereby given to charge the over payment to deposit account #500801
- 7. Execution date of the document to be recorded: 04/13/2001
- 8. Total number of pages including cover sheet: 3
- 9. I declare under penalty of perjury that to the best of my knowledge and belief, the information contained on this cover sheet is true and correct, and that any copy submitted herewith is a true and correct copy of the original document.



Date: 4/16/2001

Winston Hsu

Winston Hsu
U.S. Patent Agent
Reg. No.:41,526

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ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNORS (Inventors):

Name: Yi-Fan Chen Nationality: R.O.C.

Address: No.29-65, Lane Chiu-She, Chiu-She, Pei-Tun, Tai-Chung City, Taiwan, R.O.C.

Name: Chi-King Pu Nationality: R.O.C.

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Name: Shou-Kong Fan Nationality: R.O.C.

Address: No.Wen-Hua 1, Community 10, Shui-Kan Tsun, Chiung-Lin Hsiang, Hsin-Chu Hsien, Taiwan, R.O.C.

Hereby sells, assigns and transfers to **UNITED MICROELECTRONICS CORP.**
(hereinafter 'Assignee'), of (Assignee address)
No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C.

"BYPASS CIRCUITS FOR REDUCING PLASMA DAMAGE"

Which is found in :

- (a) _____ U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____

Assignment , 1 of 2

NPO-P0002E-US1

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this 04/02/2001 (Date of signing).

(Type name of inventor)

Signature of INVENTOR

Yi-Fan Chen

Yi-Fan Chen

Chi-King Pu

Chi-King Pu

Shou-Kong Fan

Shou-Kong Fan

Assignment, Page 2 of 2

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